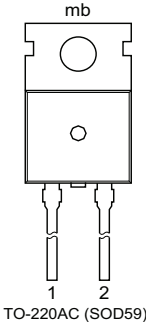
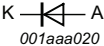


5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                         | Simplified outline   | Graphic symbol  |
|-----|--------|-------------------------------------|--|---|
| 1   | K      | cathode                             |  |  |
| 2   | A      | anode                               |  |   |
| mb  | mb     | mounting base; connected to cathode |  |   |

6. Ordering information

Table 3. Ordering information

| Type number | Package  |   |         |
|-------------|----------|---|---------|
|             | Name     | Description   | Version |
| BYC10-600   | TO-220AC | plastic single-ended package; heatsink mounted;<br>1 mounting hole; 2-lead TO-220AC | SOD59   |

7. Marking

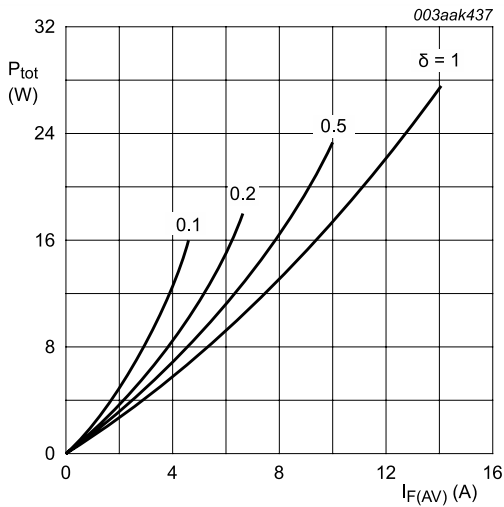
Table 4. Marking codes

| Type number | Marking codes |
|-------------|---------------|
| BYC10-600   | BYC10-600     |

8. Limiting values

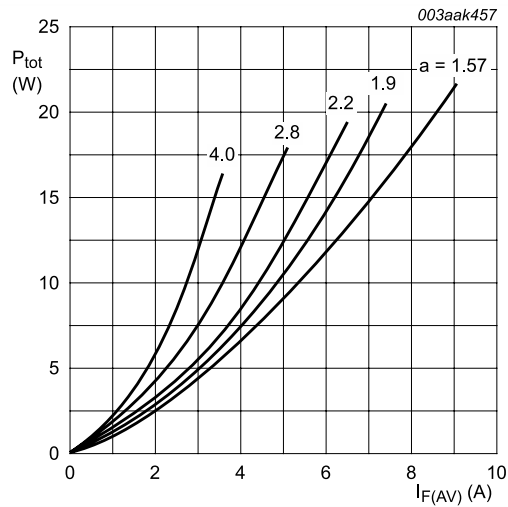
Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol      | Parameter                           | Conditions  | Values     | Unit               |
|-------------|-------------------------------------|---|------------|--------------------|
| $V_{RRM}$   | repetitive peak reverse voltage     |   | 600        | V                  |
| $V_{RWM}$   | crest working reverse voltage       |   | 600        | V                  |
| $V_R$       | reverse voltage                     | $T_{mb} \leq 114\text{ }^{\circ}\text{C}$   | 500        | V                  |
| $I_{F(AV)}$ | average forward current             | $\delta = 0.5$ ; $T_{mb} \leq 78\text{ }^{\circ}\text{C}$ ; square-wave pulse;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> | 10         | A                  |
| $I_{FRM}$   | repetitive peak forward current     | $\delta = 0.5$ ; $T_{mb} \leq 78\text{ }^{\circ}\text{C}$ ; square-wave pulse   | 20         | A                  |
| $I_{FSM}$   | non-repetitive peak forward current | $t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse   | 65         | A                  |
|             |                                     | $t_p = 8.3\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse  | 71         | A                  |
| $T_{stg}$   | storage temperature                 |   | -40 to 150 | $^{\circ}\text{C}$ |
| $T_j$       | junction temperature                |   | 150        | $^{\circ}\text{C}$ |



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$   
 $V_o = 1.300\text{ V}$ ;  $R_s = 0.050\text{ }\Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$   
 $V_o = 1.300\text{ V}$ ;  $R_s = 0.050\text{ }\Omega$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter  | Conditions             |  | Min | Typ | Max | Unit |
|----------------|--|------------------------|--|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base    | <a href="#">Fig. 3</a> |  | -   | -   | 2   | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient free air | in free air            |  | -   | 60  | -   | K/W  |

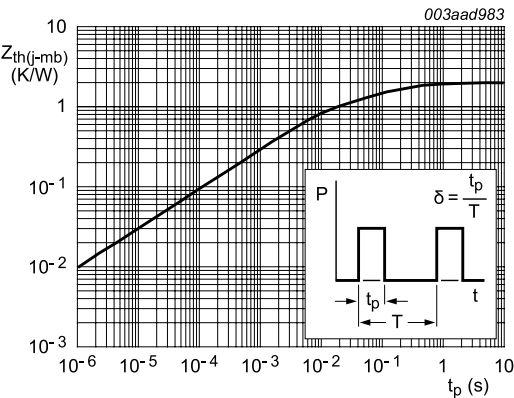
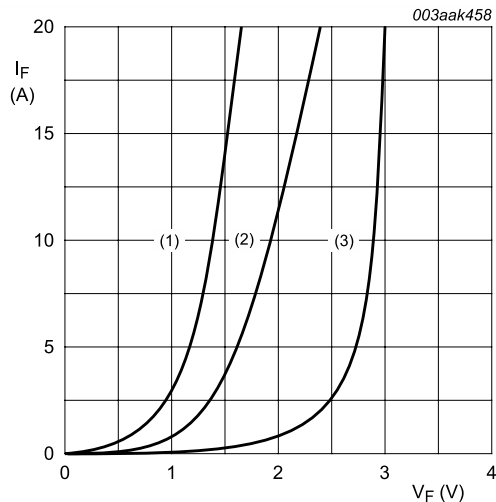


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

## 10. Characteristics

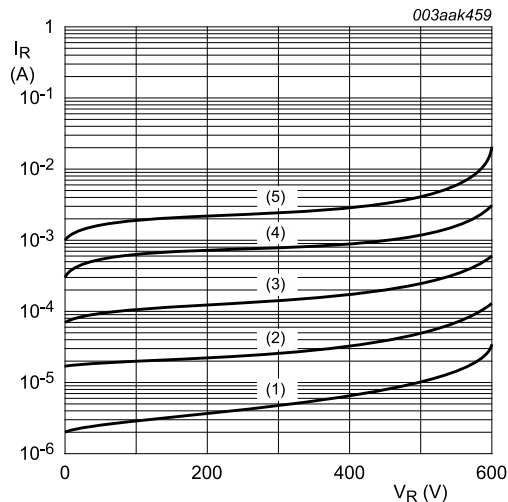
Table 7. Characteristics

| Symbol                  | Parameter                     | Conditions   |  | Min | Typ | Max | Unit |
|-------------------------|-------------------------------|--|--|-----|-----|-----|------|
| Static characteristics  |                               |  |  |     |     |     |      |
| V <sub>F</sub>          | forward voltage               | I <sub>F</sub> = 10A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 4</a>   |  | -   | 2   | 2.9 | V    |
|                         |                               | I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 4</a>   |  | -   | 1.4 | 1.8 | V    |
|                         |                               | I <sub>F</sub> = 20 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 4</a>   |  | -   | 1.7 | 2.3 | V    |
| I <sub>R</sub>          | reverse current               | V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>   |  | -   | 9   | 200 | μA   |
|                         |                               | V <sub>R</sub> = 500 V; T <sub>j</sub> = 100 °C; <a href="#">Fig. 5</a>  |  | -   | 1.1 | 3   | mA   |
| Dynamic characteristics |                               |  |  |     |     |     |      |
| t <sub>rr</sub>         | reverse recovery time         | I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>     |  | -   | 35  | 55  | ns   |
|                         |                               | I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>  |  | -   | 19  | -   | ns   |
|                         |                               | I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 100 °C; <a href="#">Fig. 6</a> |  | -   | 32  | 40  | ns   |
| I <sub>RM</sub>         | peak reverse recovery current | I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 125 °C; <a href="#">Fig. 6</a> |  | -   | 3   | 7.5 | A    |
|                         |                               | I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 125 °C; <a href="#">Fig. 6</a> |  | -   | 9.5 | 12  | A    |
| V <sub>FRM</sub>        | forward recovery voltage      | I <sub>F</sub> = 10 A; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>                          |  | -   | 8   | 11  | V    |



(1)  $T_j = 150\text{ }^{\circ}\text{C}$ ; typical values  
(2)  $T_j = 150\text{ }^{\circ}\text{C}$ ; maximum values  
(3)  $T_j = 25\text{ }^{\circ}\text{C}$ ; maximum values  
 $V_o = 1.300\text{ V}$ ;  $R_s = 0.050\text{ }\Omega$

Fig. 4. Forward current as a function of forward voltage



(1)  $T_j = 25\text{ }^{\circ}\text{C}$ ; typical values;  
(2)  $T_j = 50\text{ }^{\circ}\text{C}$ ; typical values;  
(3)  $T_j = 75\text{ }^{\circ}\text{C}$ ; typical values;  
(4)  $T_j = 100\text{ }^{\circ}\text{C}$ ; typical values;  
(5)  $T_j = 125\text{ }^{\circ}\text{C}$ ; typical value

Fig. 5. Reverse leakage current as a function of reverse voltage; typical values

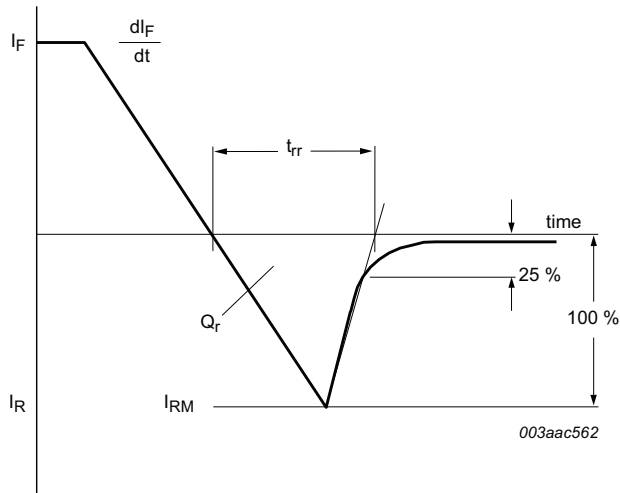


Fig. 6. Reverse recovery definitions; ramp recovery

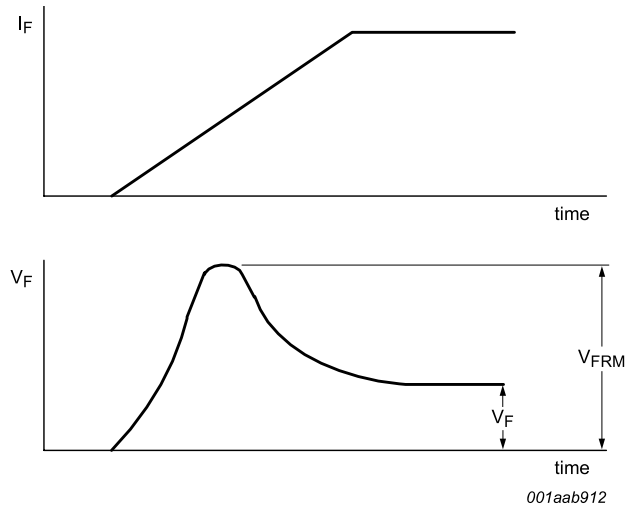
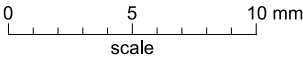
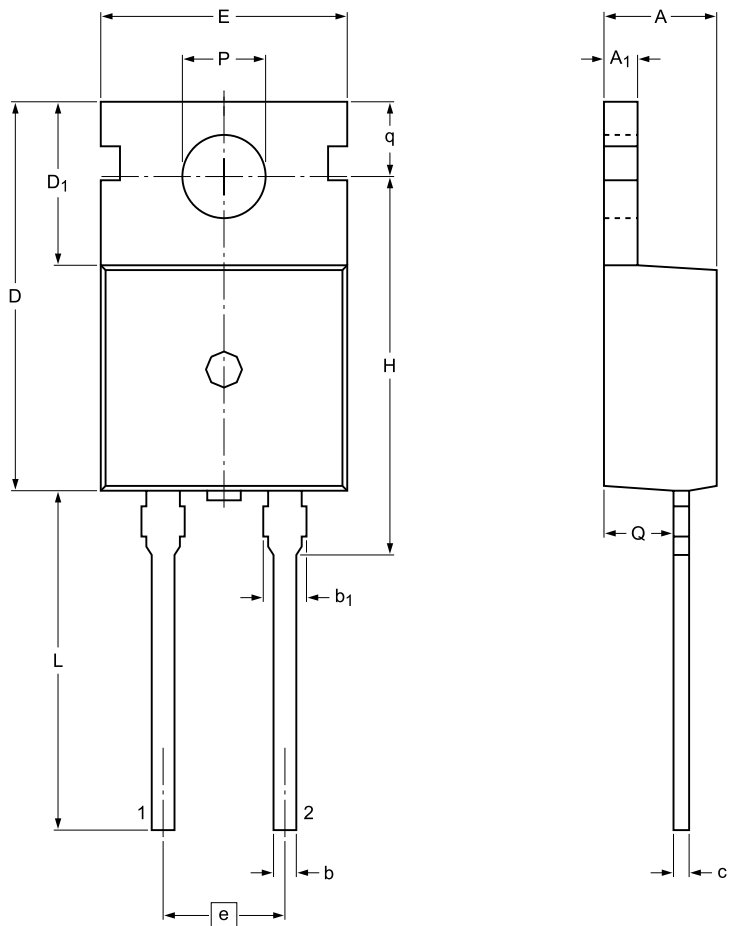


Fig. 7. Forward recovery definitions

11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59



Dimensions

| Unit | A   | A <sub>1</sub> | b    | b <sub>1</sub> (1) | c    | D    | D <sub>1</sub> | E     | e     | H     | L    | P    | Q   | q   |
|------|-----|----------------|------|--------------------|------|------|----------------|-------|-------|-------|------|------|-----|-----|
| max  | 4.7 | 1.40           | 0.95 | 1.7                | 0.65 | 15.8 | 6.8            | 10.30 | 5.08  | 16.25 | 15.0 | 3.80 | 2.6 | 2.9 |
| nom  |     |                |      |                    |      |      |                |       | (REF) |       |      |      |     |     |
| min  | 4.3 | 1.15           | 0.70 | 1.3                | 0.45 | 15.6 | 6.4            | 9.65  |       | 15.70 | 12.5 | 3.65 | 2.2 | 2.7 |

Note

1. Protruded dambar are included in the dimension.

sod059\_po

| Outline version | References      |       |       |  | European projection | Issue date                      |
|-----------------|-----------------|-------|-------|--|---------------------|---------------------------------|
|                 | IEC             | JEDEC | JEITA |  |                     |                                 |
| SOD59           | 2-lead TO-220AC |       |       |  |                     | <del>09-08-25</del><br>12-11-27 |

## 12. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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- [1] Please consult the most recently issued document before initiating or completing a design.
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